

JUN 09 1998

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SUITE 1111

06-16-1998

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RECORDATION COVER SHEET - PATENT APPLICATION

6/8/98

NAME OF CONVEYING PARTY	:	Jih-Wen CHOU and Tony LIN
NAME OF RECEIVING PARTY	:	United Microelectronics Corp.
ADDRESS OF RECEIVING PARTY	:	No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.
NATURE OF CONVEYANCE	:	Assignment of U.S. patent application
CONVEYANCE EXECUTION DATE	:	August 22, 1997
PATENT APPLICATION NO.	:	09/009,335
APPLICATION FILED TOGETHER WITH THIS DOCUMENT	:	NO
APPLICATION EXECUTION DATE	:	August 22, 1997
CORRESPONDENCE ADDRESS	:	RABIN & CHAMPAGNE, P.C. 1725 K Street, N.W., Suite 1111 Washington, D.C. 20006
ATTORNEY REFERENCE	:	JIA 542
TOTAL NUMBER OF PATENTS AND APPLICATIONS INVOLVED	:	One
TOTAL FEE PAID	:	\$40.00
METHOD OF PAYMENT	:	<input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account

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In the event there is attached hereto no check, or a check for an insufficient amount, please charge the fee to our Account No. 18-0002 and notify us accordingly.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Robert H. Berdo, Jr.
(Registration No. 38,075)

May 27, 1998
Date

RHB/dmb

Total number of pages including cover sheet, attachments and document: 3

PATENT
REEL: 9237 FRAME: 0306

ASSIGNMENT

WHEREAS, (1) Jih-Wen Chou (2) Tony Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD OF FABRICATING AN AIR-GAP SPACER OF A METAL-
OXIDE-SEMICONDUCTOR DEVICE

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature Jih-Wen Chou

8/22/97
date

Signature Tony Lou

8/22/97
date

Signature _____

date _____

Signature _____

date _____